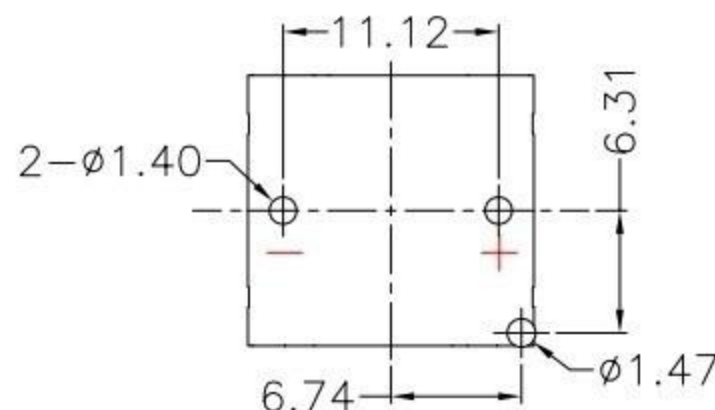
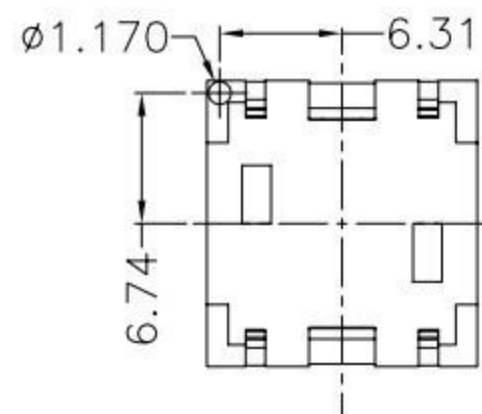
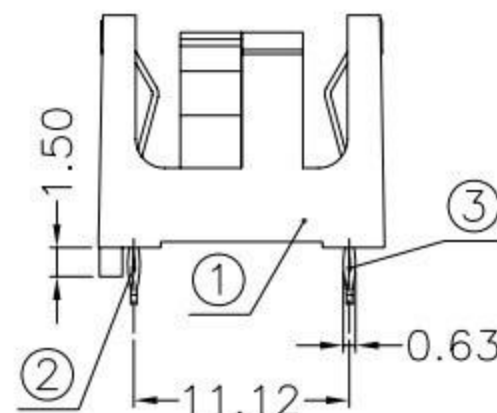
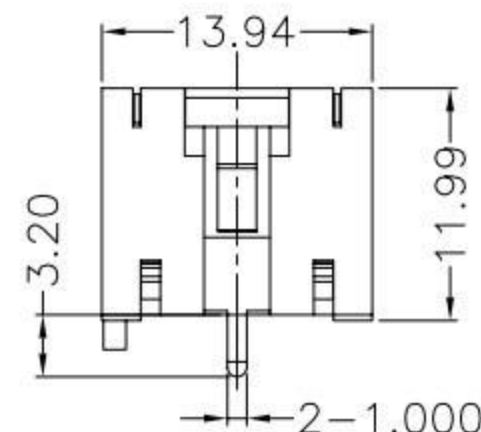
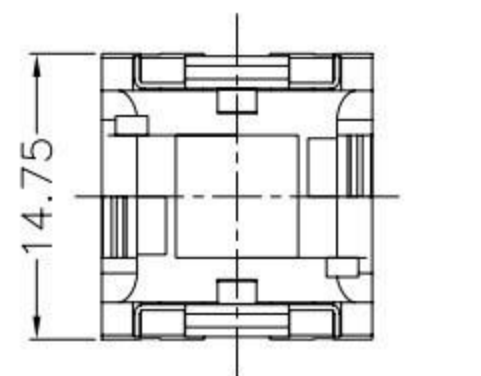




REV.	ECN NO.	REVISED	DATE



PCB Layout Diagram
Top View

1.MATERIAL:

- a.HOUSING:PPA
- b.CONTACT:PHOSPHOR BRONZE
(SURFACE PLATING:Au1u")

SEE ORDERING INFORMATION

2.ELECTRIC:

- a.CONTACT RESISTANCE: 30 MILLIOHMS MAX
- b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN
- c.DIELECTNIC VOLTAGE: 500V AC ONE SEC LEVEL
- d.OPERATING TEMPERATURE: -25°C~ +85°C

ORDERING INFORMATION

电池座系列
PLATING:
A-Au1U"
J-Ni100U"~120U"
K-Sn100U"~120U"

DIP 90° TYPE

MATERIAL:
1A-PBT BLACK
1B-PA66 BLACK
2A-PPA BROWN
2B-PPA BLACK
3A-PPS BROWN
3B-PPS BLACK
4A-LCP WHITE
4B-LCP BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES				东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.			
DECIMALS:	ANGLES:	DSND	DATE	2017-07-13	TITLE:		
X :±0.30	X :±1°	CHKD	DATE	2017-07-13			
X.X :±0.25	X.X :±0.5°	APVD	DATE	2017-07-13	PART NO.:		
X.XX :±0.20							
X.XXX :±0.10							
WEIGHT: 1.91g				SCALE: 2:1	SIZE: A4	VIEW: ④ ⑤	
SHEET 1 OF 1				UNIT: mm	REV.: A/0	OBJECT: MY	DRAW NO.

NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR
3	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.30mm	Gold Plating and Ni Under-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.30mm	Gold Plating and Ni Under-Plating
1	HOUSING	1	PPA	BLACK